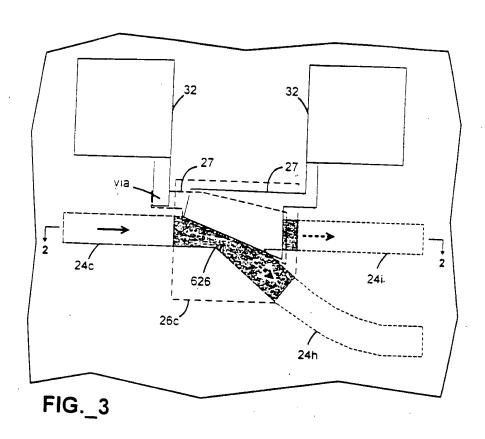


FIG._2



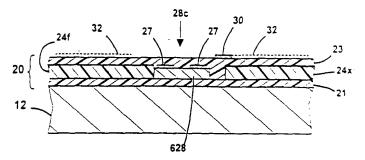


FIG._4-1

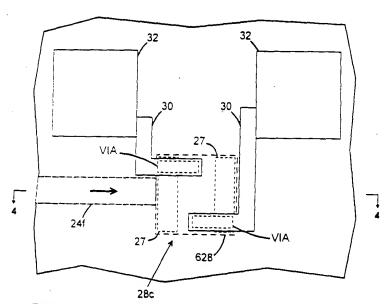
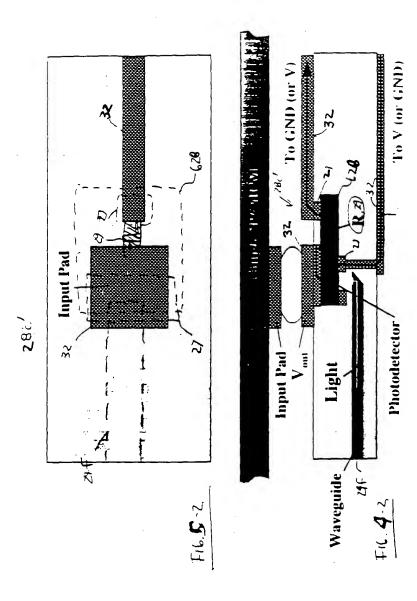
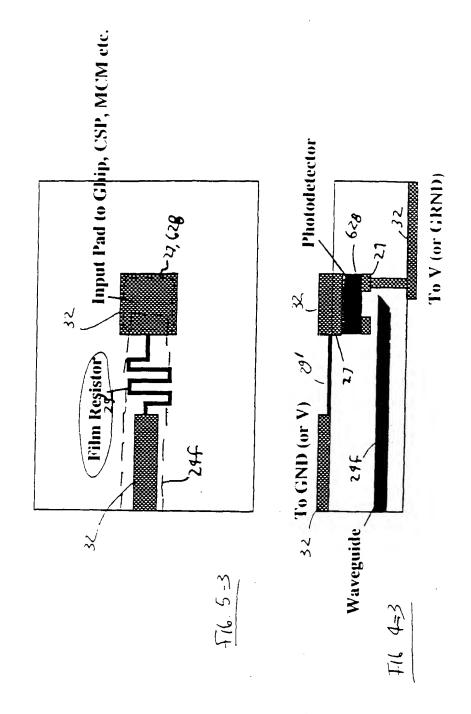
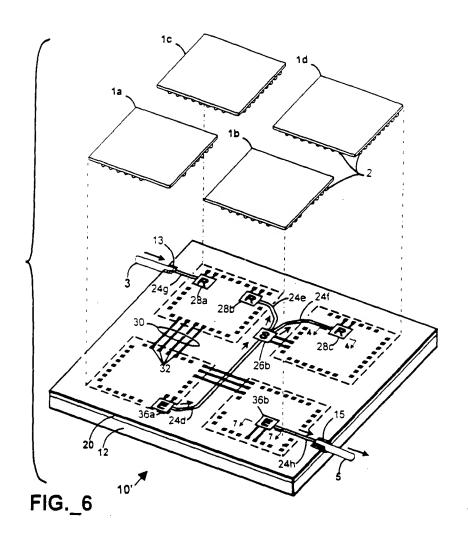


FIG._5-1







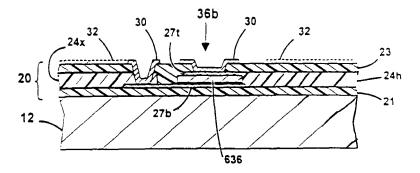
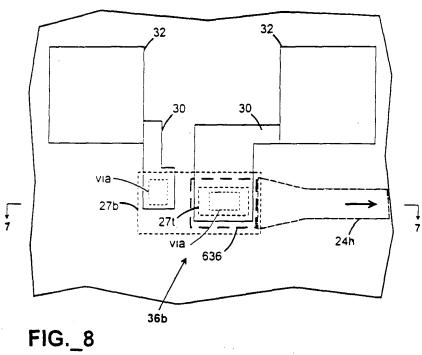
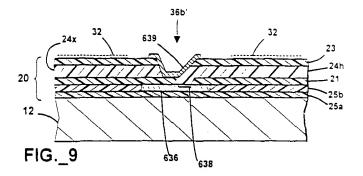


FIG._7





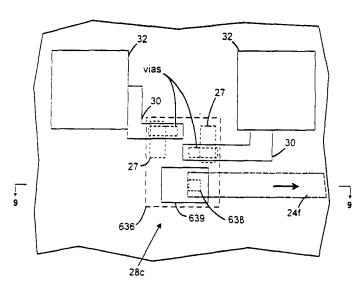
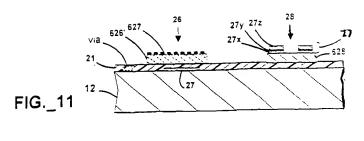
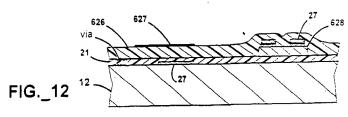
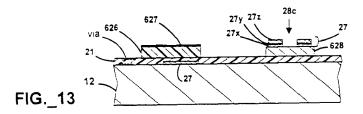
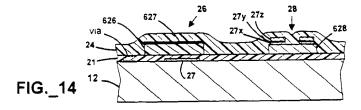


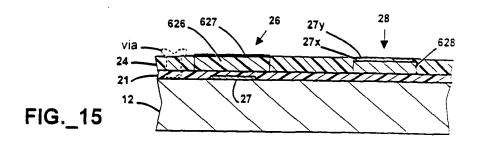
FIG._10

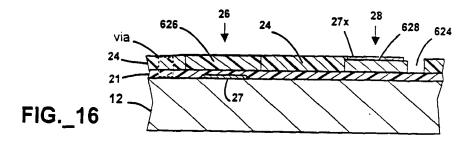


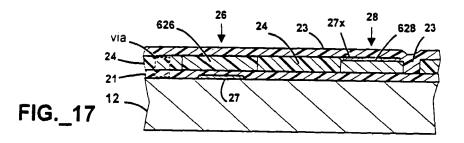


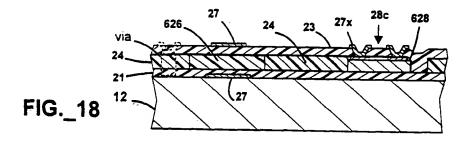


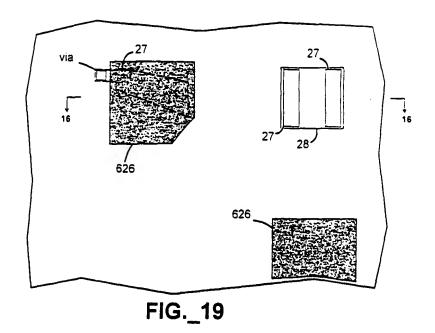




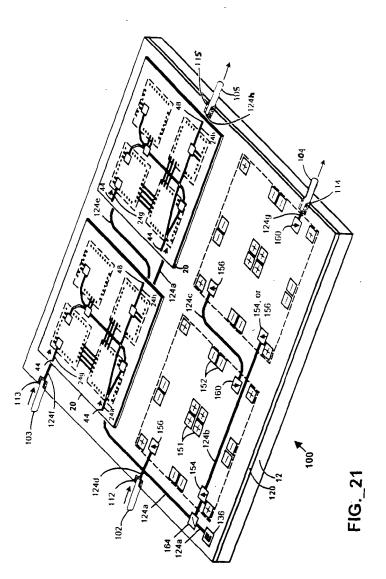








27 27 27 27 28 24 28 16 626 FIG._20



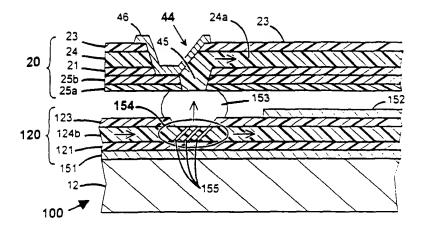


FIG._22

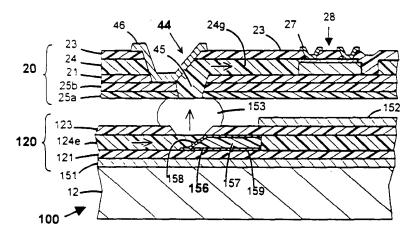


FIG._23

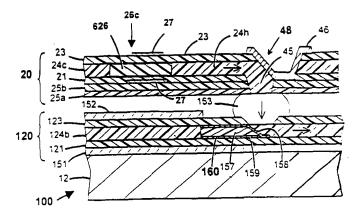
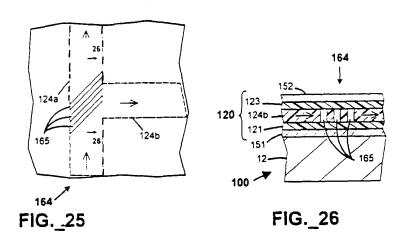
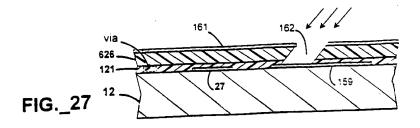
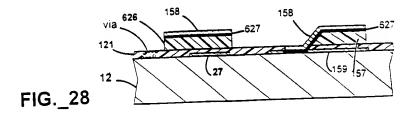
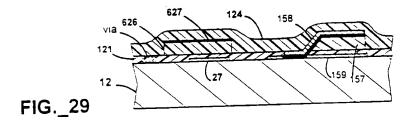


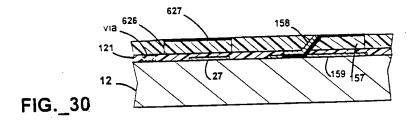
FIG._24

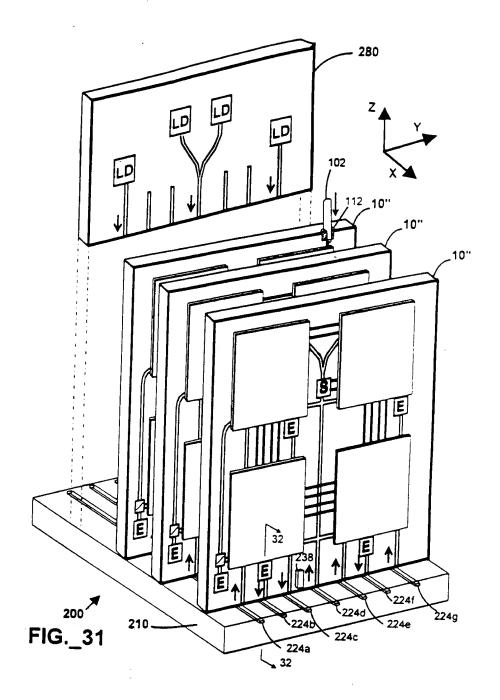


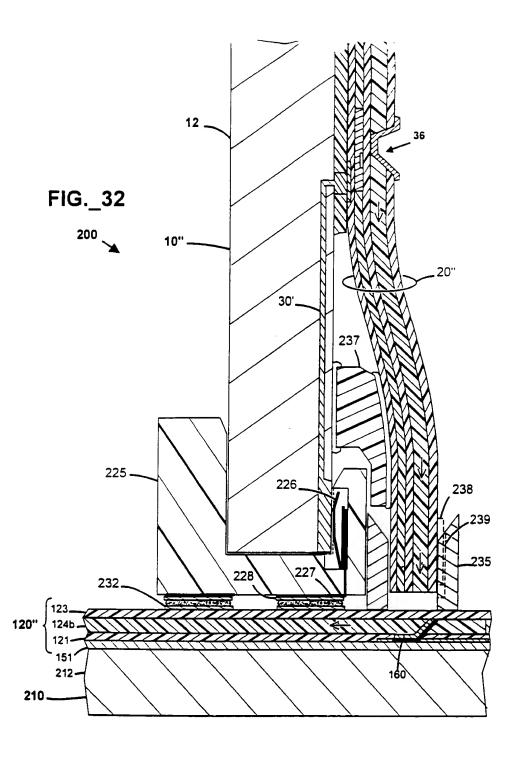


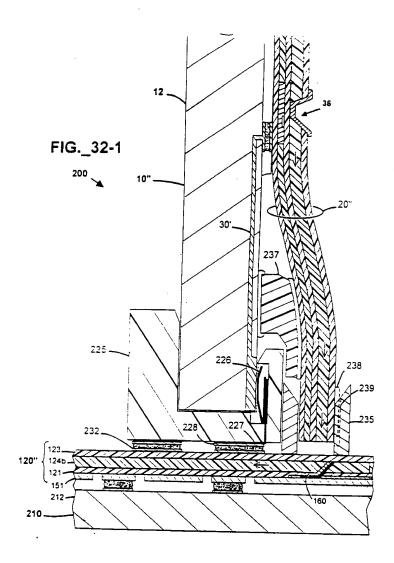


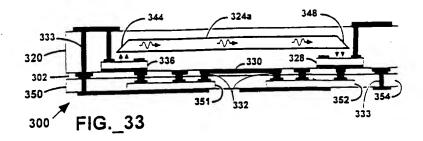


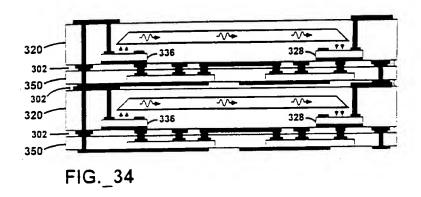


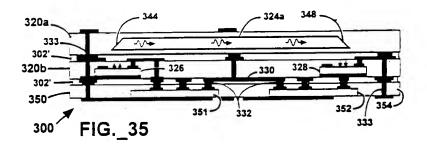












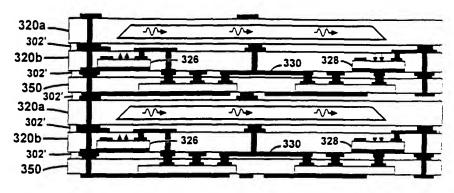
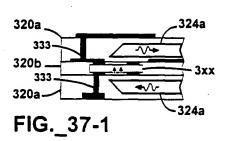
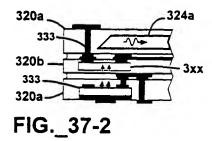
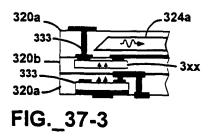


FIG._36







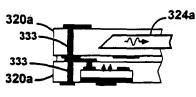


FIG._37-4

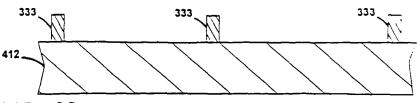


FIG._38

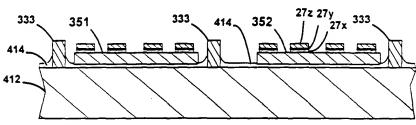


FIG._39

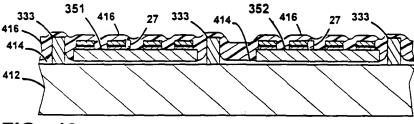


FIG._40

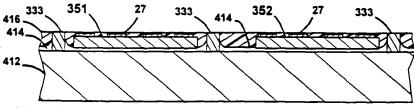


FIG._41

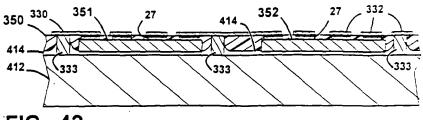


FIG._42

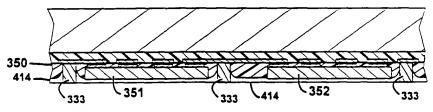


FIG._43

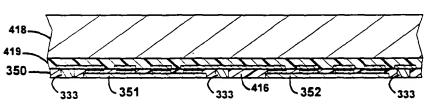


FIG._44

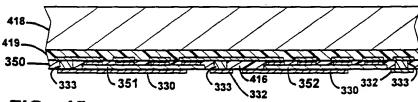
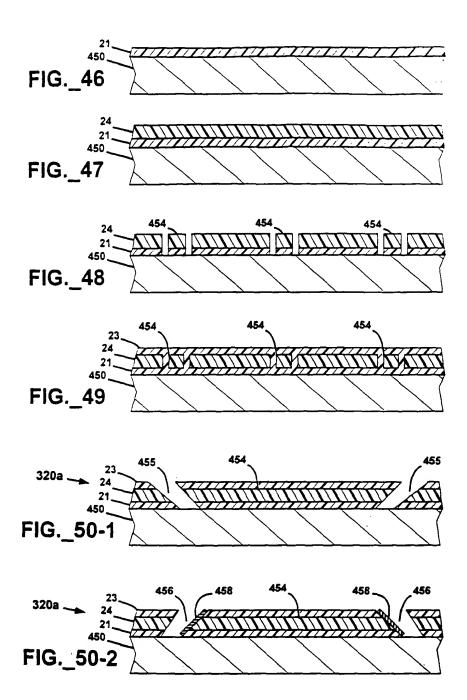
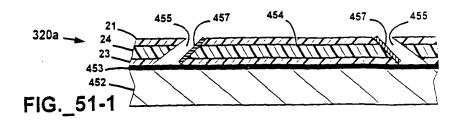
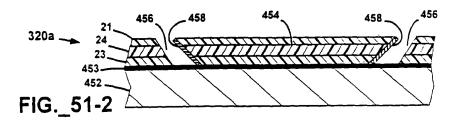
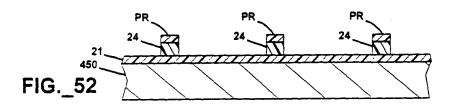


FIG._45









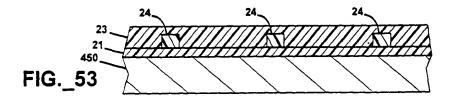
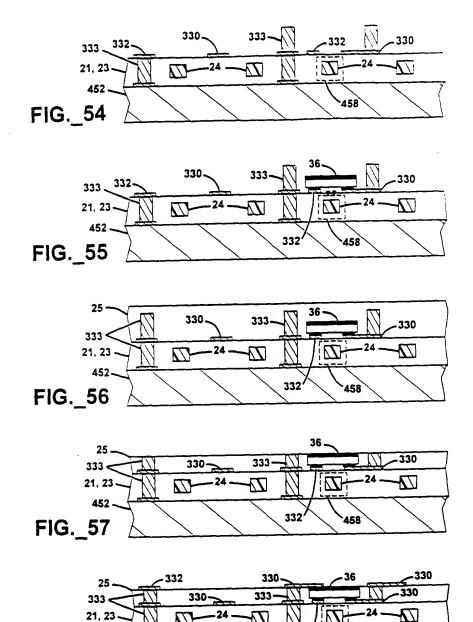
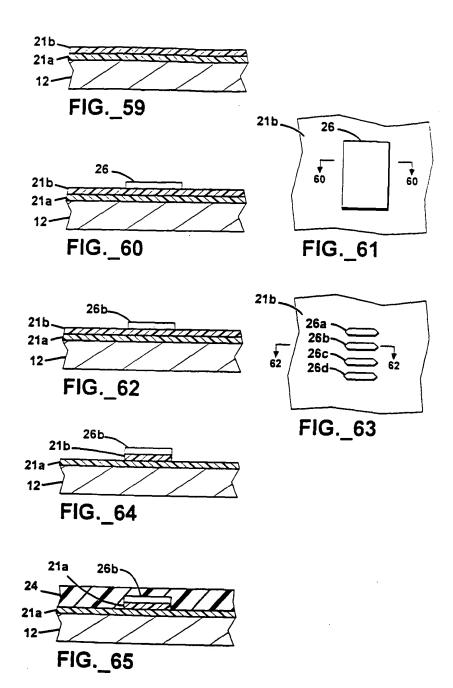
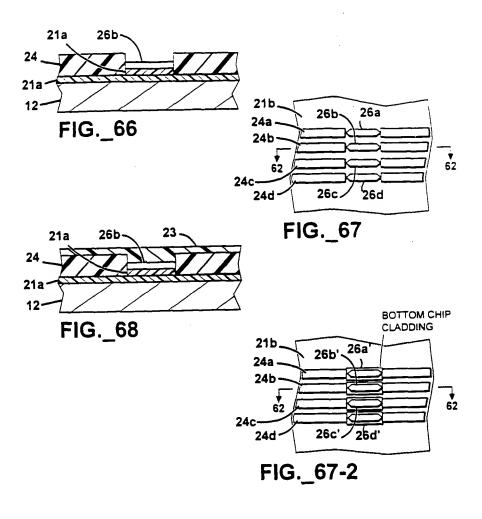
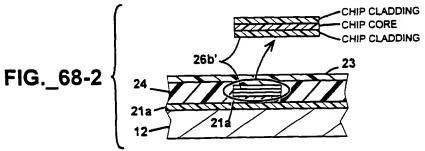


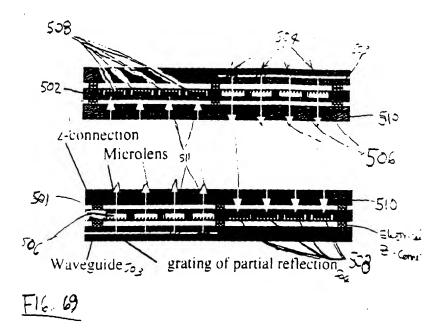
FIG. 58

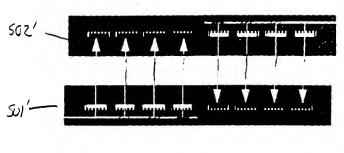




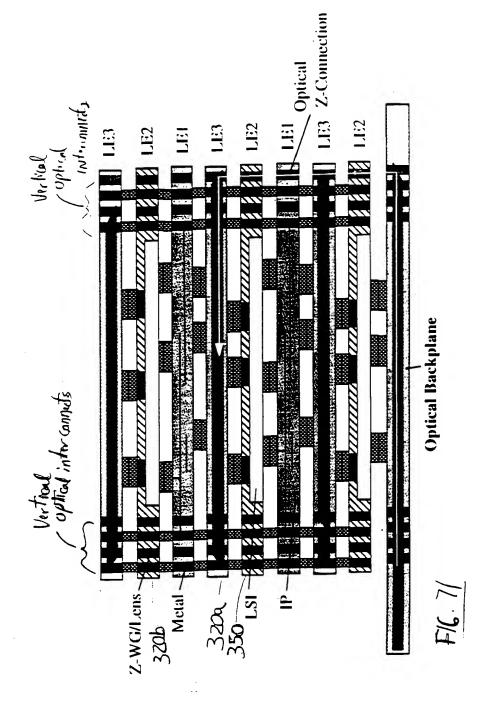


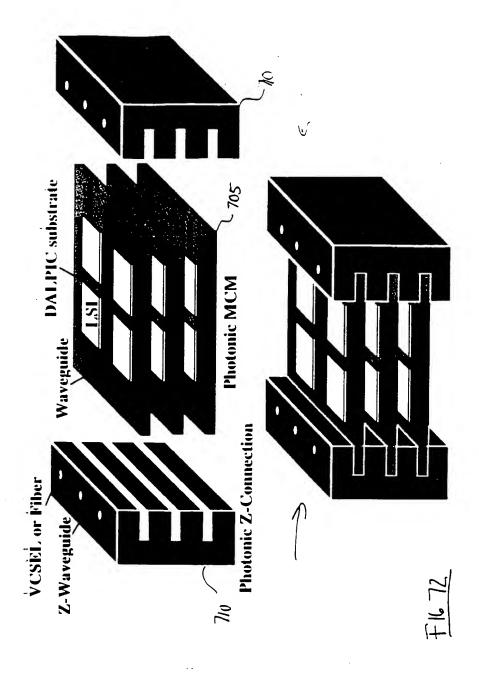


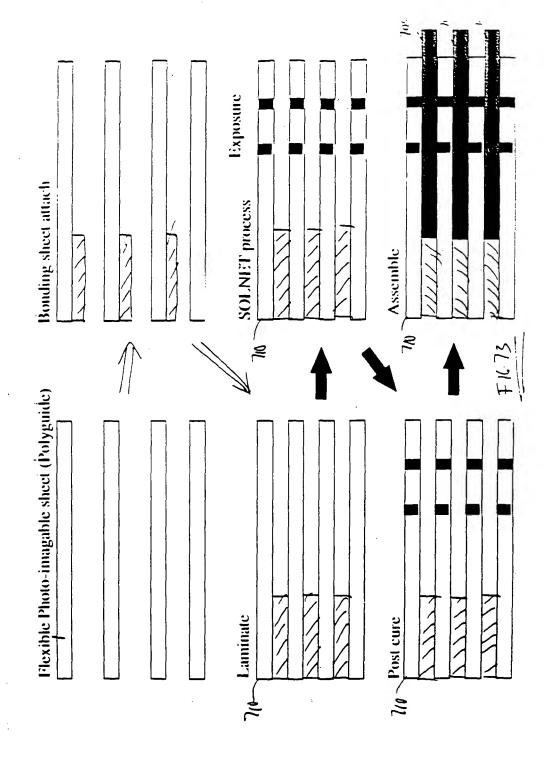




F16. 70







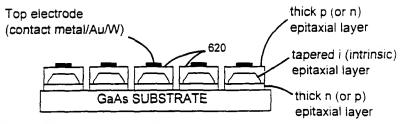
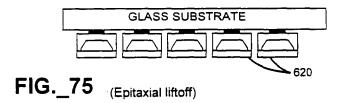


FIG. 74 (Epitaxial growth and patterning)



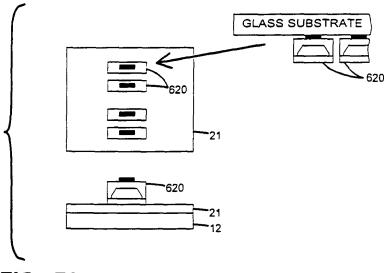
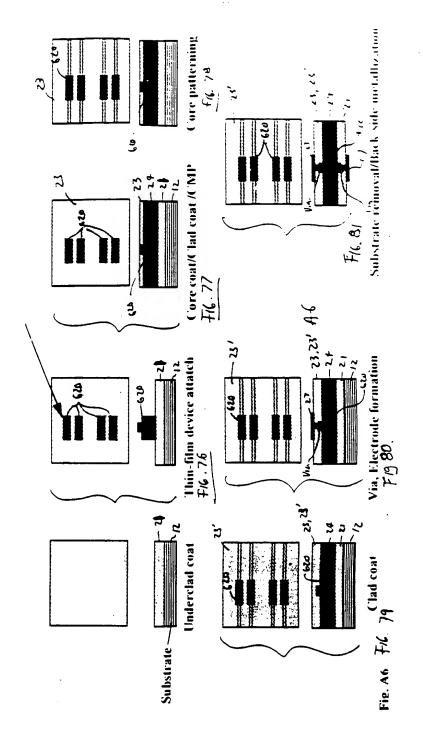
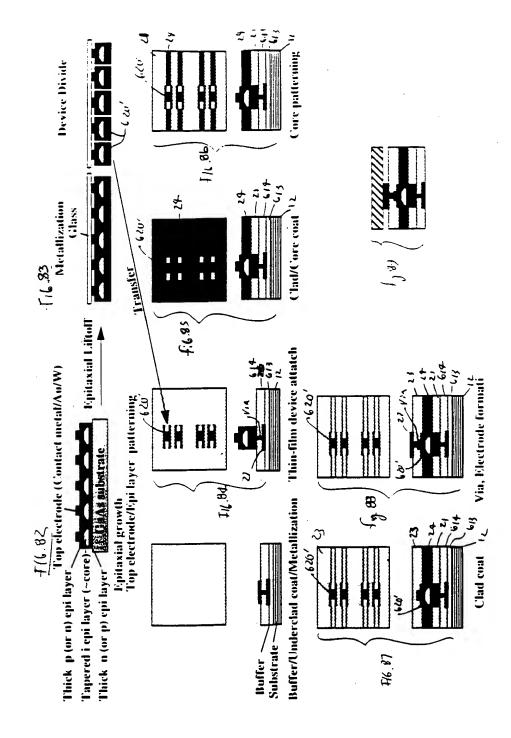
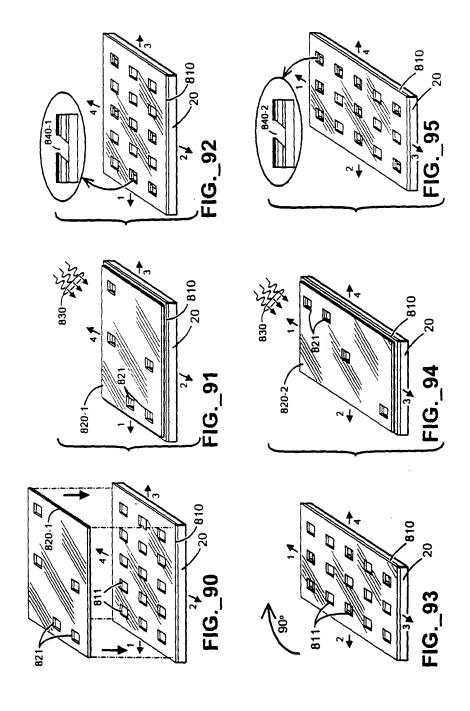
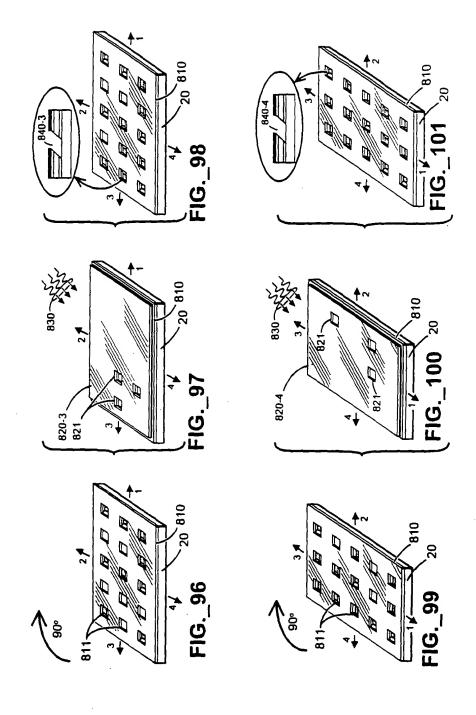


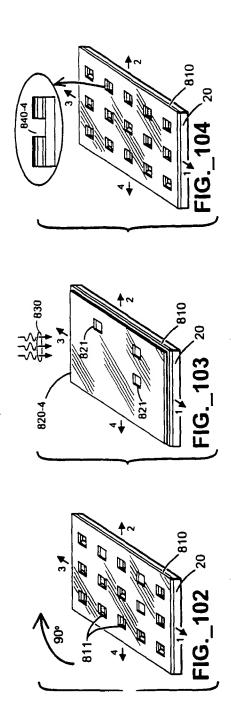
FIG._76 (Transfer)

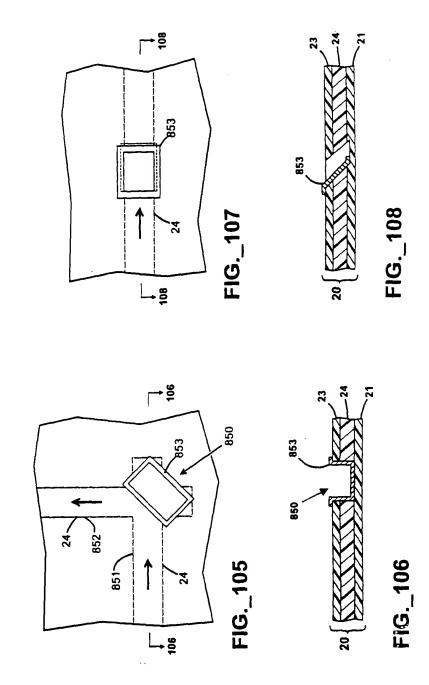










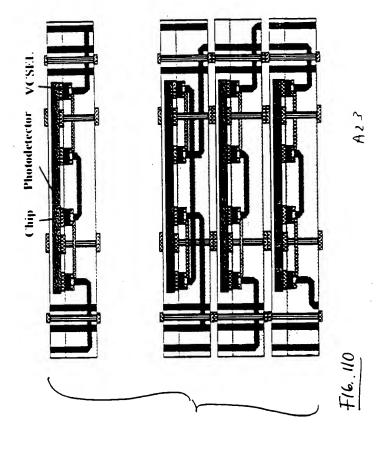


GS CX/CXX OE Solution --- OE-3D-Stack FUITSU Computer Packaging Technologies, Inc.

FCPT

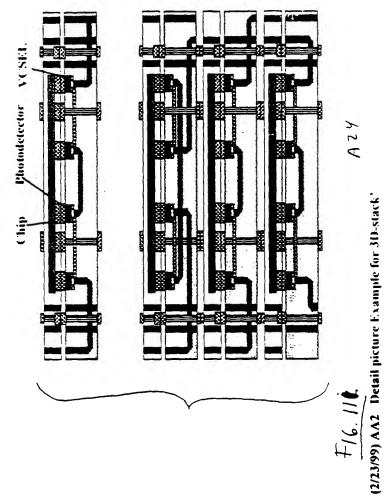
OE-film-H 9 12 OE-film-DW(V) or (M) Chip Layer (Film-Chip Integration) Opt- Z-Connection (Z-WG/Lens) Metal-

2/23/99-added 7



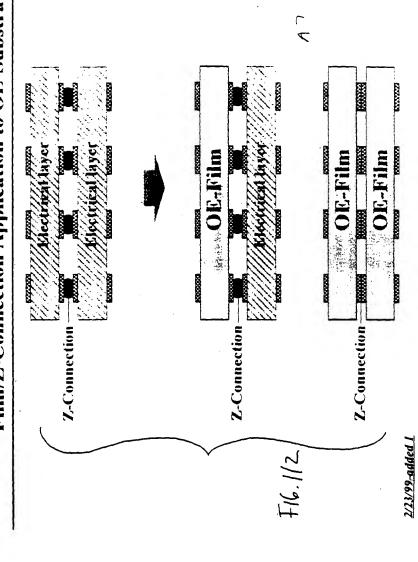
(2/23/99) AA1 Detail picture Example for 3D-stack

(New version of the AA1 of 2/5/99)



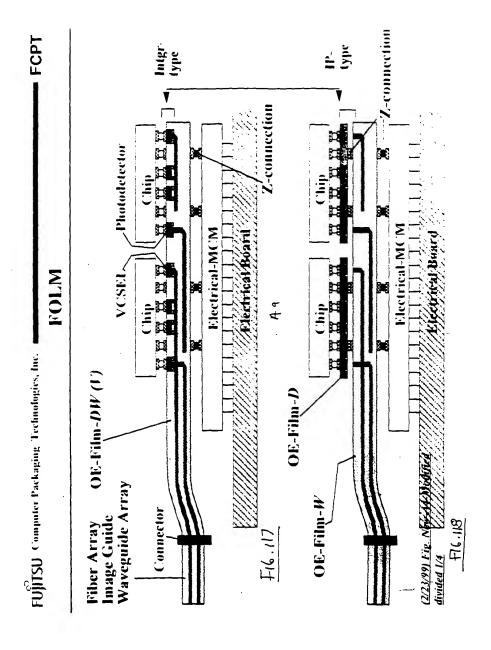
(New version of the AA2 of 2/5/99)

Film/Z-Connection Application to OE-Substrate FUJTSU Computer Packaging Technologies, Inc.



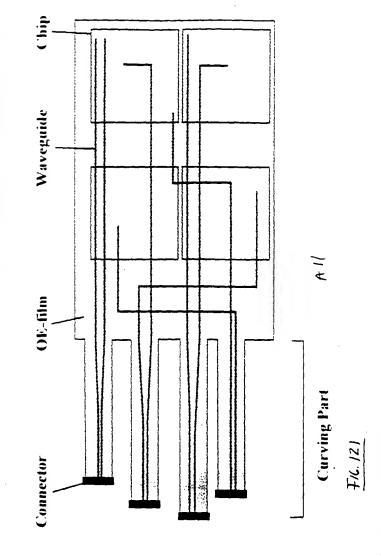
450



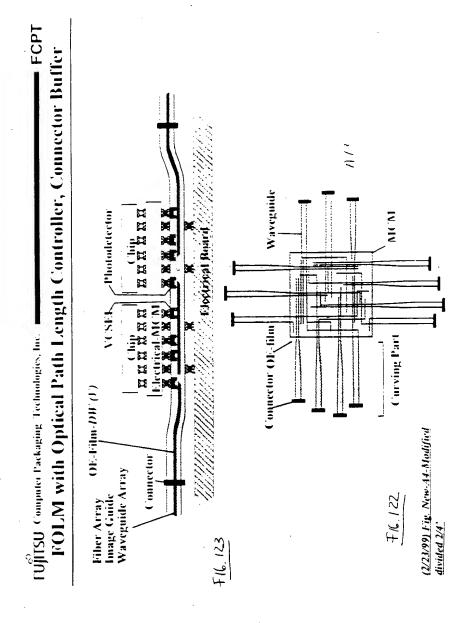


FCPT Z-connection Z-connection HHHHHHH Photodetector Electrical-MCM FOLM Chip II II II II II **VUSELY** HHHHHHH Electrical-MCM A 10 FUJISU Computer Packaging Technologies, Inc. OE-Film-DW (V) OE-Film-D OE-Film-W Image Guide Waveguide Array Fiber Array 2D Virtical F16.4120 F16.119

- FCPT FOLM with Optical Path Length Controller, Connector Buffer FUJITSU Computer Packaging Technologies, Inc.



(2/17/99) Fig. New-A4-Modified divided 2/4

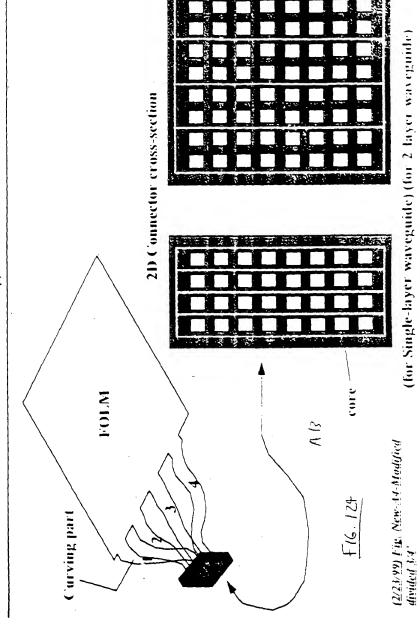


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FUMISU Computer Packaging Technologies, Inc.

FCPT

FOLM with 2D Waveguide Connector

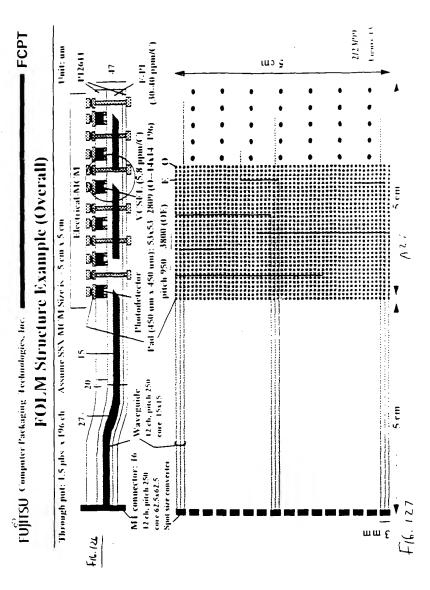


FOLM: High-Speed Option FUJITSU Computer Packaging Technologies, Inc.

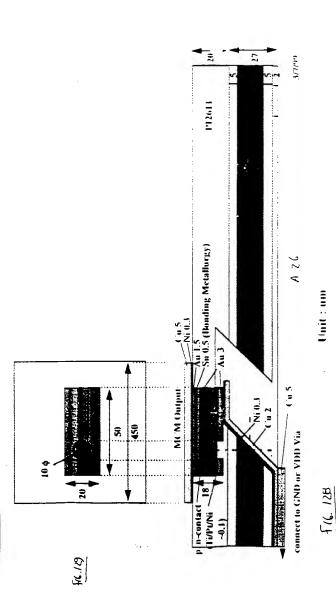
External Light Light Modulator Z-Connection Chip (MCM, CSP) OE-film-DH(AI) Photodetector Array Waveguide Fiber Ribbon Image guide Connector

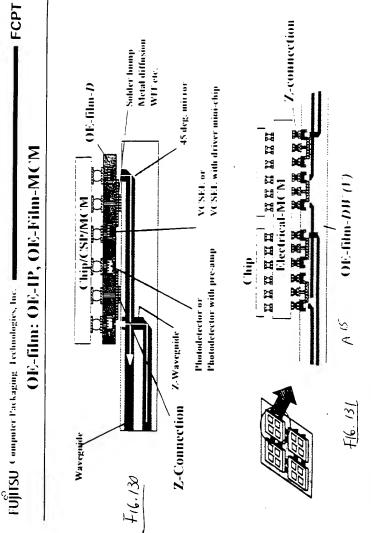
•

(2/12/29) Fig. New-11-Madified divided 43



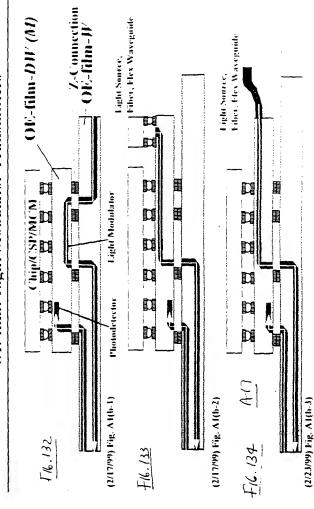
FOLM Structure Example (VCSEL part) 10JTSU Computer Packaging Technologies, Inc.



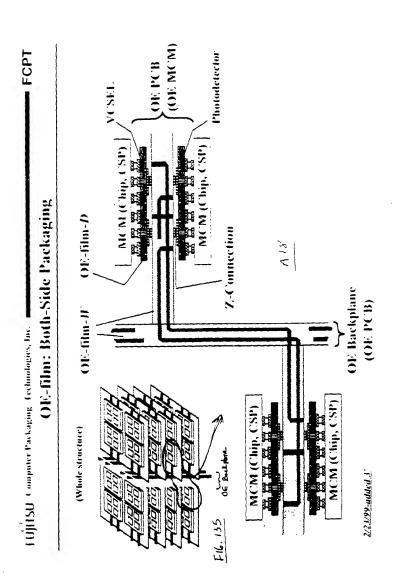


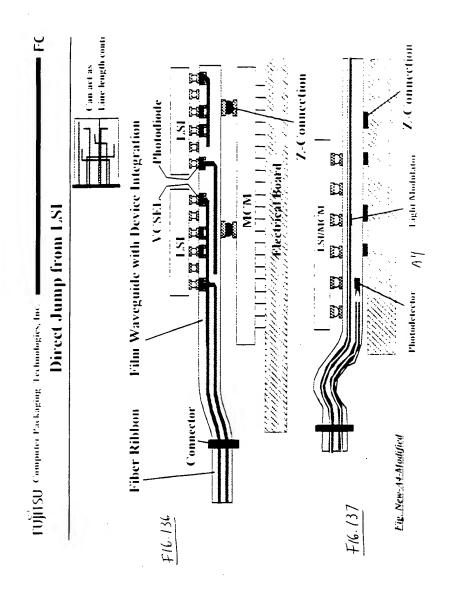
(2/23/99) Fig. New-A1-Modified

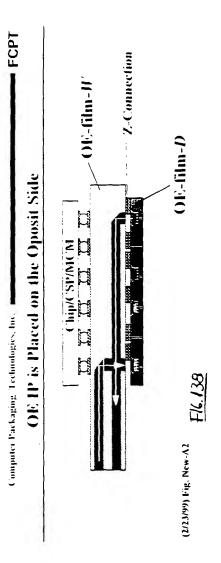




Examples of Light Modulators: Electro-Optic (E.O.) Modulator, Ulectro Absorption (UA) Modulator







N 20

OE MCM FUJITSU Computer Packaging Technologies, Inc.

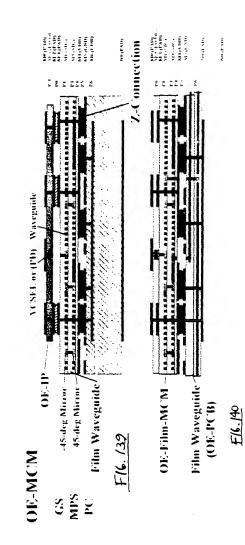


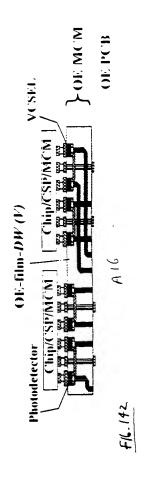
Fig. A5-Modified

■ FCPT FUJITSU Computer Packaging Technologies, Inc.

OE-film: Smart Pixel

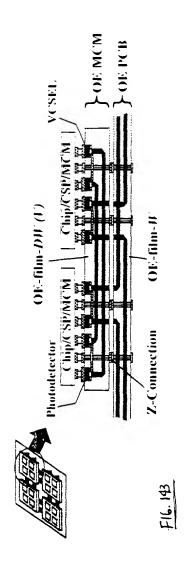
The part of the part of the District of the Di

F/6 /4



2/23/99-udded 6

■ FCP OE-Film/OE-Film Stack --- Back-Side Connection 1 Of 150 Computer Packaging Technologies, Inc.

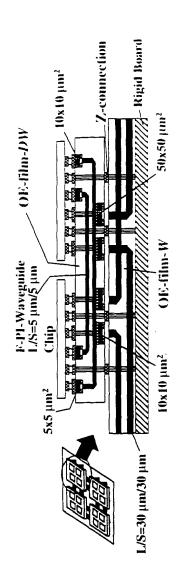


418

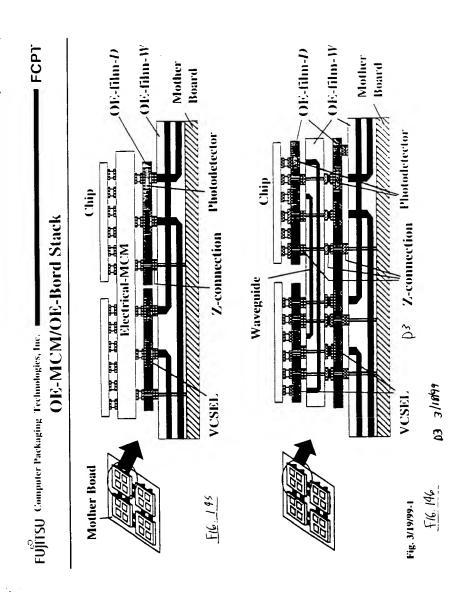
2/2.1/99-added 4°

OE-Film/OE-Film Stack --- Back-Side Connection FUJTSU Computer Packaging Technologies, Inc.

FCPT

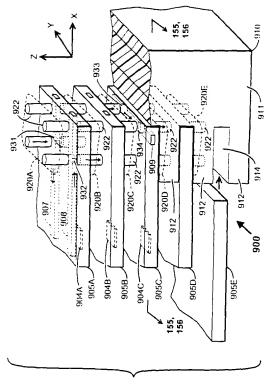


F16.144

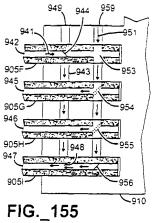


• FCPT F16 150 Com Manual Fil. 198 661 713 Device Integration Process OE-film-D - (6') Jump to the waveguide formation process - (5) Vias/Pads/Lines formation FUJITSU Computer Packaging Technologies, Inc. (I) Pads/Lines formation ¬▼ (6) Substrate removal (2) Placement of Thin film devices (3) Polymer coat (4) Planarization

OE-film DW(I)



IG. 154



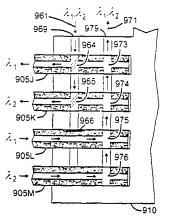


FIG._156-1

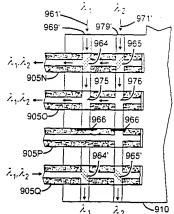
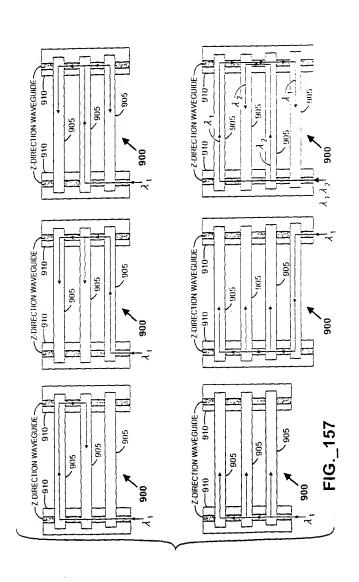
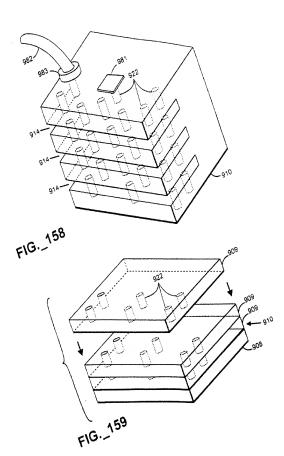
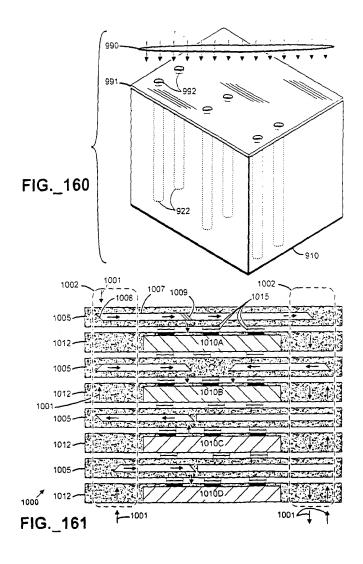
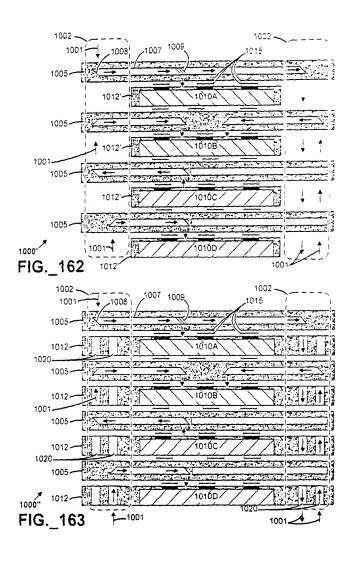


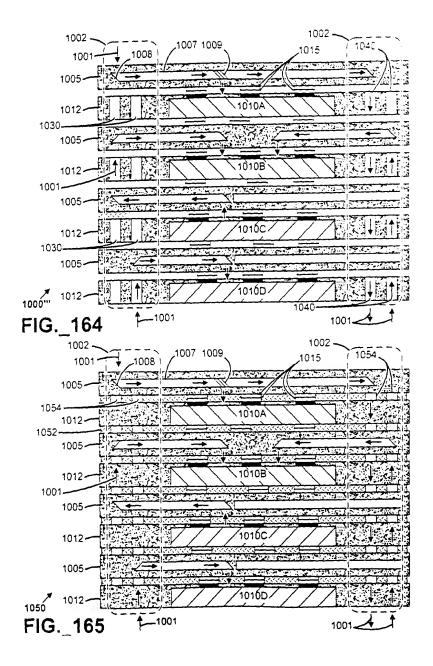
FIG._156-2

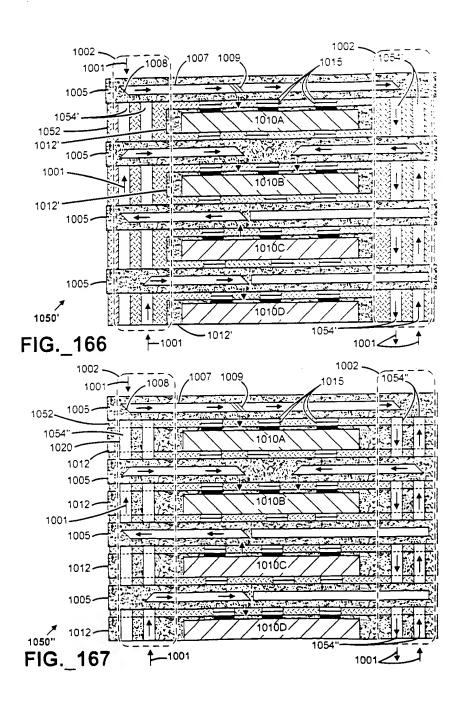


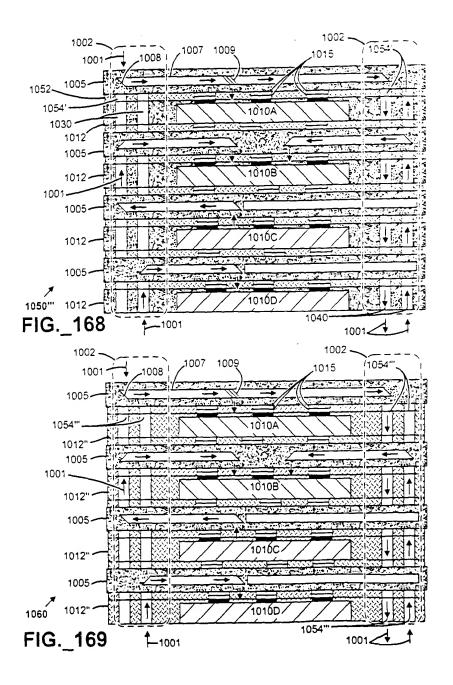


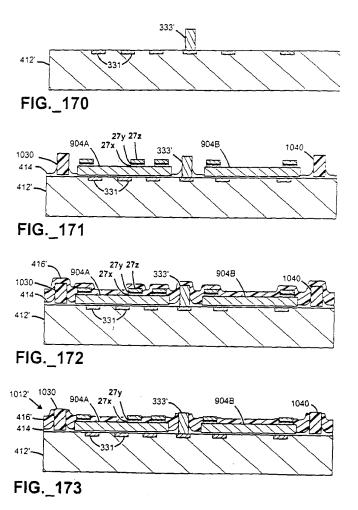












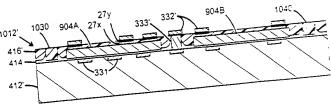


FIG._174

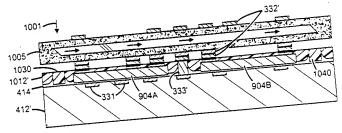


FIG._175

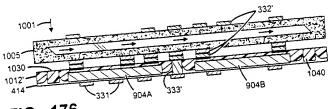


FIG._176

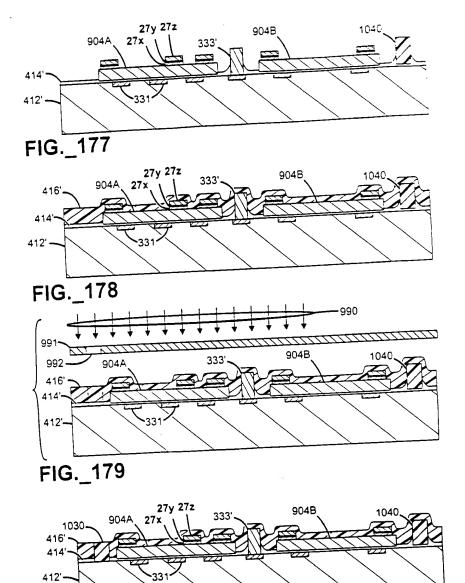
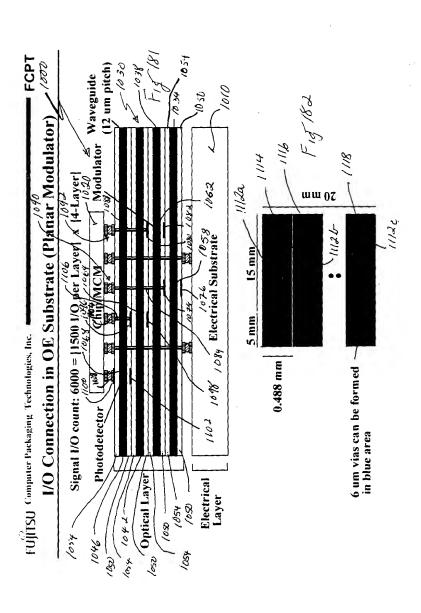
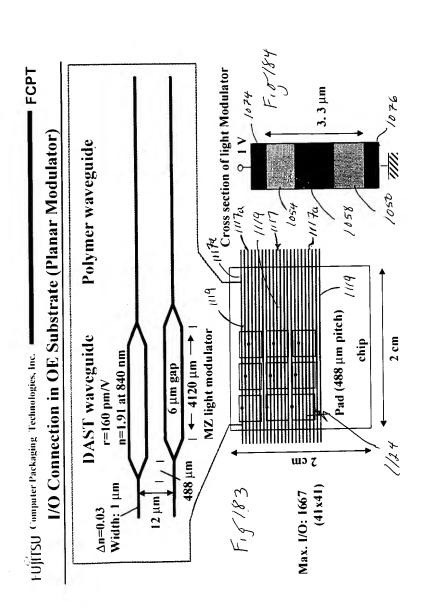


FIG._180

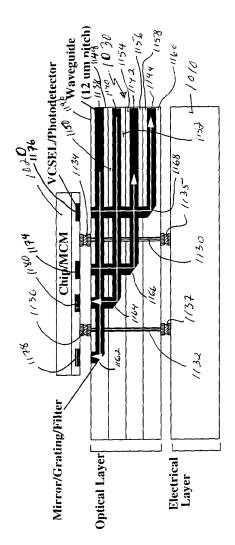




FUJITSU Computer Packaging Technologies, Inc.

I/O Connection in OE Substrate (OE-VLSI)

Signal I/O count: $6000 = [1500 \text{ I/O per Layer}] \times [4-\text{Layer}]$

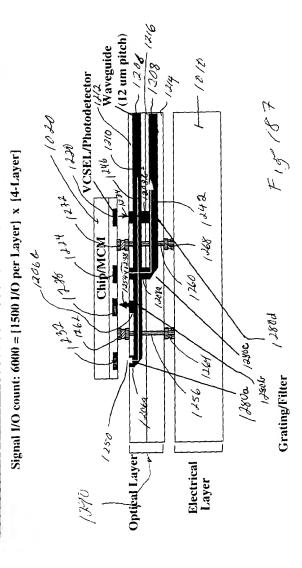


F19 185

FUJTSU Computer Packaging Technologies, Inc.

(12 um pitch) 1154 Waveguide 1152 1142 VCSEL/Photodetector 041/ 8511 カカンノ 1157 1160 I/O Connection in OE Substrate (OE-VLSI) Signal I/O count: $6000 = [1500 \text{ I/O per Layer}] \times [4-\text{Layer}]$ 1178 4511 0811 V/135 Chip/MCM , 4611/ 1130C 1908// MI 12511 95.11 11326 1/34 Mirror/Grating/Filter 1166 Electrical Layer Optical Layer a_{κ} 120EL 1 war

I/O Connection in OE Substrate (OE-VLSI, WDM) FUJITSU Computer Packaging Technologies, Inc.



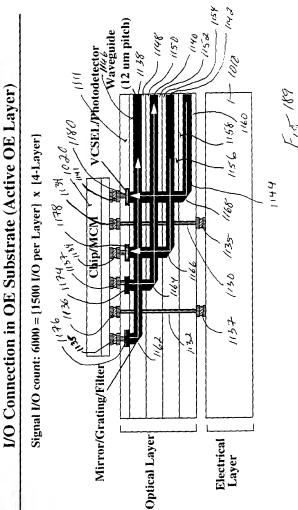
FUJTSU Computer Packaging Technologies, Inc.

(12 um pitch) 11/2 Waveguide 1,25 (020) 1242 VCSEL/Photodetector I/O Connection in OE Substrate (OE-VLSI, WDM) Signal I/O count: $6000 = [1500 \text{ I/O per Layer}] \times [4-\text{Layer}]$ |2066 - |7084|12066 1856/258 1220 Electrical Layer Optical Layer

Grating/Filter

TODE





FCP1

FUJITSU Computer Packaging Technologies, Inc.

I/O Connection in OE Substrate (Active OE Layer)

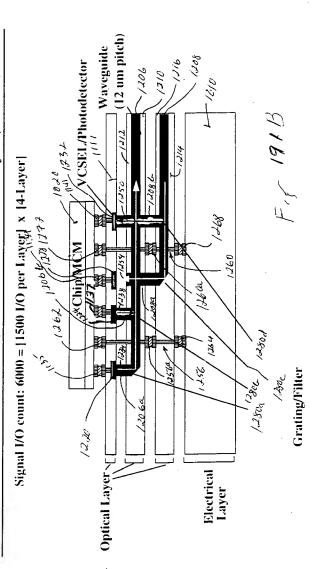
1(12 um pitch) Waveguide VCSEL/Photodetector 1150 1160 4411 11.58 -1142 1158 1136 1180 4 1176 1136 1030 1111 Signal I/O count: $6000 = [1500 \text{ I/O per Layer}] \times [4-Layer]$ Chip/MCM 1130 -1137 Mirror/Grating/Filter Electrical Layer Optical Layer – 1000

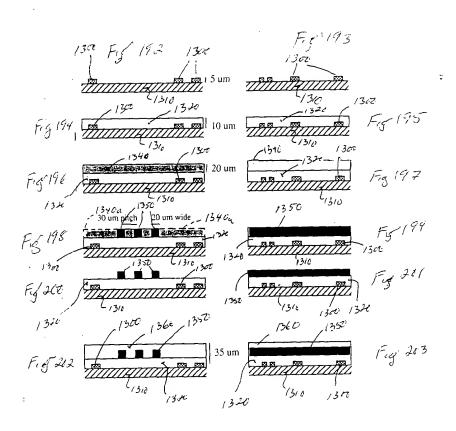
I/O Connection in OE Substrate (Active OE Layer, WDM) FUITSU Computer Packaging Technologies, Inc.

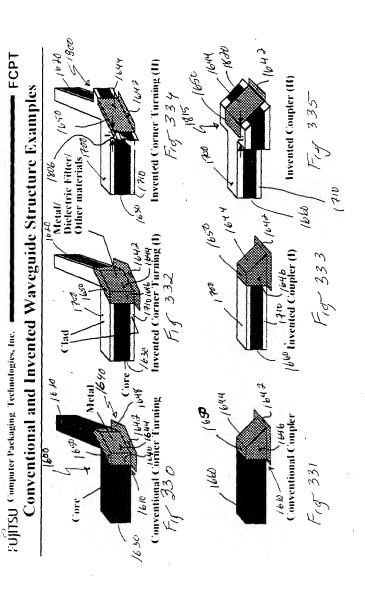
Waveguide //12 um pitch) VCSEL/Photodetector 0781 de01 Signal I/O count: 6000 = [1500 I/O per Layer] x [4-Layer] HEE! 1998 (3006 12802 (2816) Optical Layer Electrical Layer

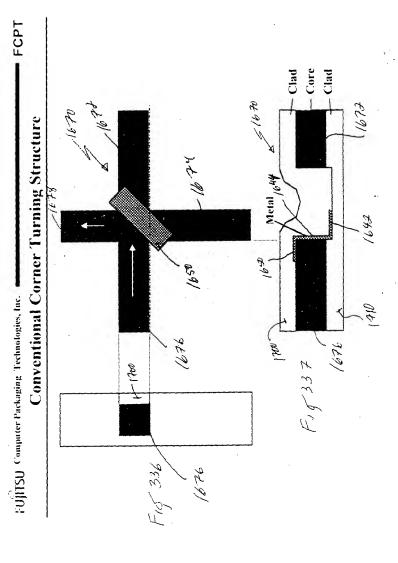
/280c \ Grating/Filter /280d

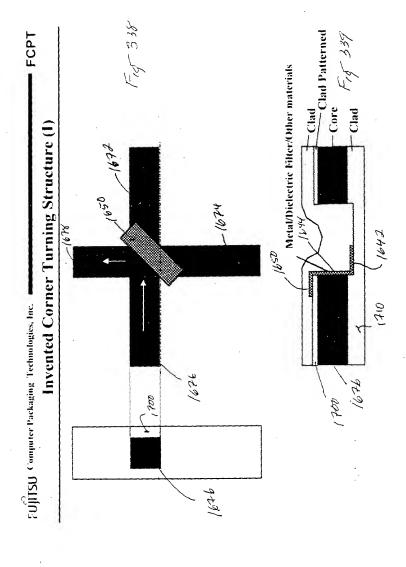
■ FCPT I/O Connection in OE Substrate (Active OE Layer, WDM) FUJITSU Computer Packaging Technologies, Inc.

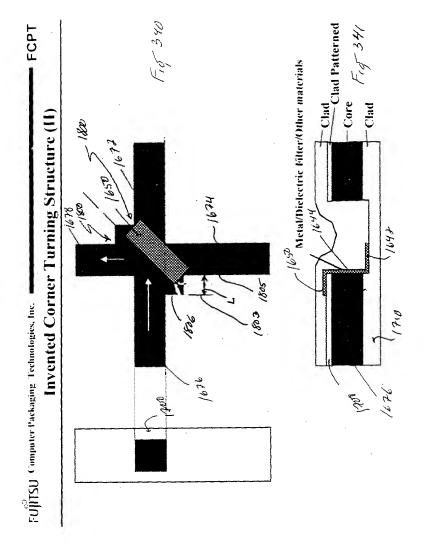


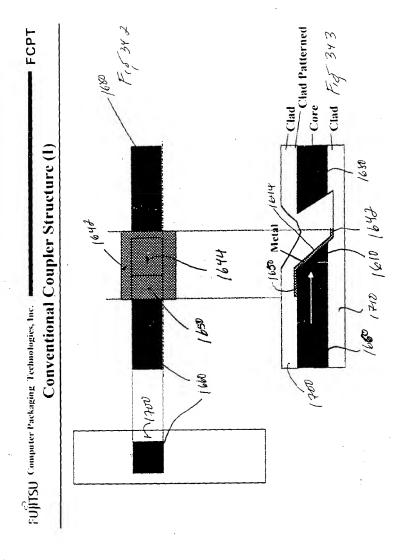


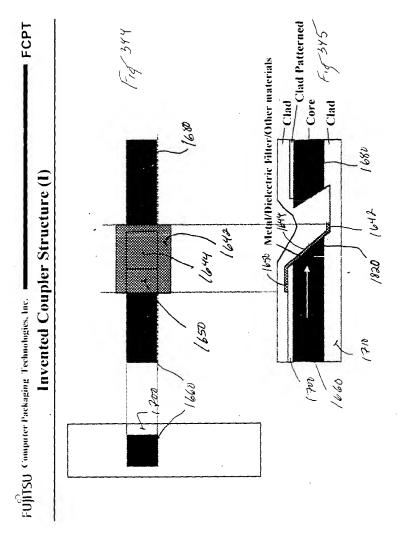


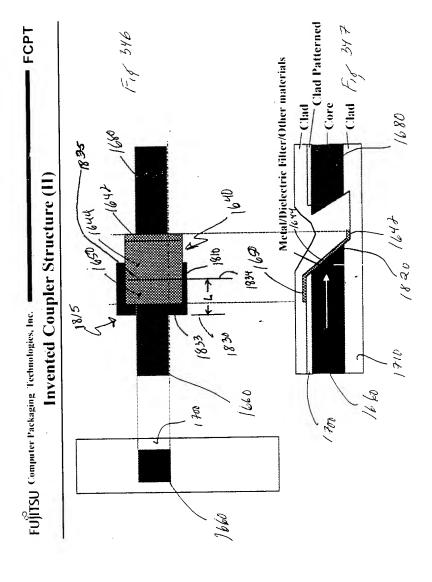






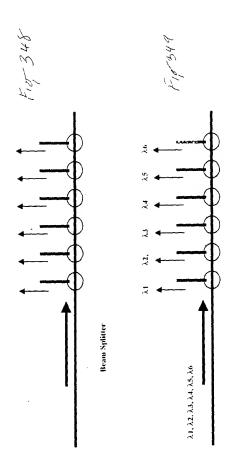




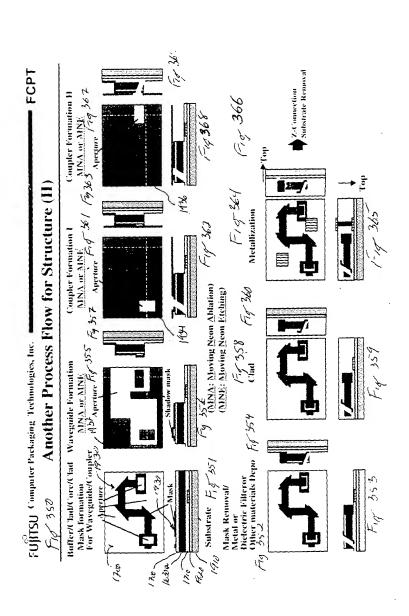


Exeimer Laser Ablation Example for Beveled Cut (2) FUJITSU Computer Packaging Technologies, Inc. .

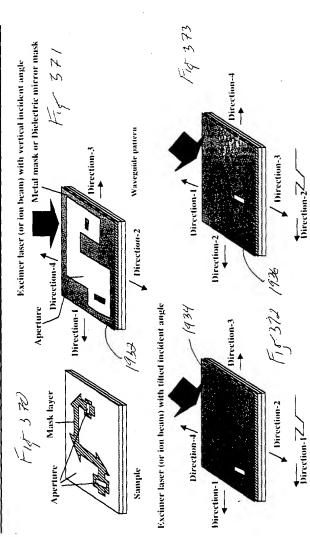
• FCPT

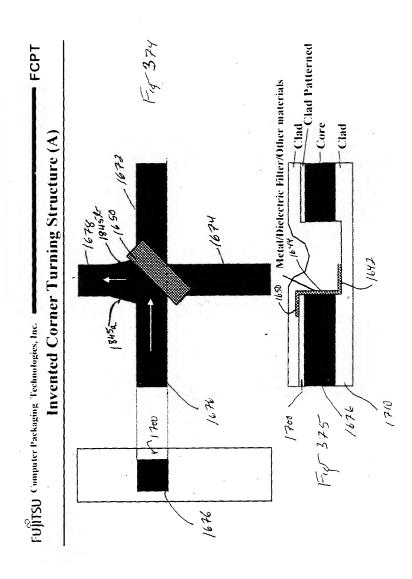


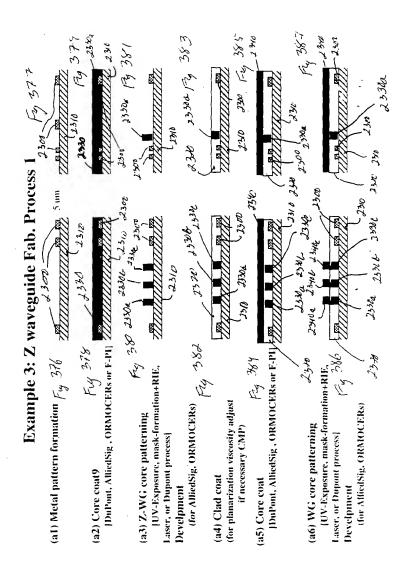
WDM DEMAX

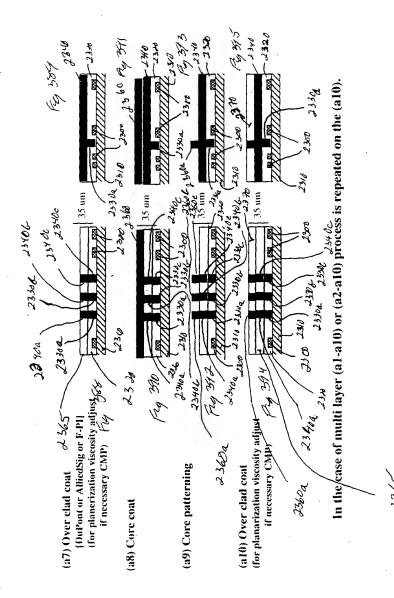


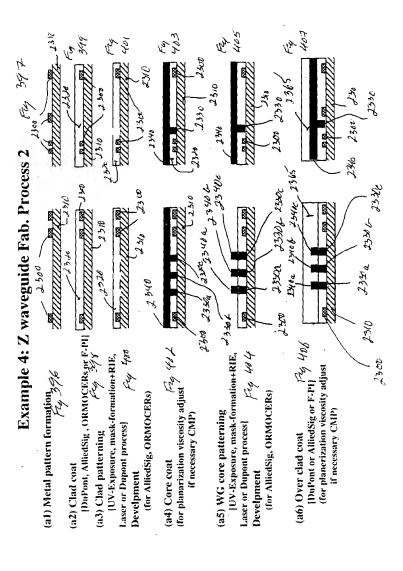
■ FCPT MNA, MNE Example for Add2 example FUJTSU Computer Packaging Technologies, Inc.

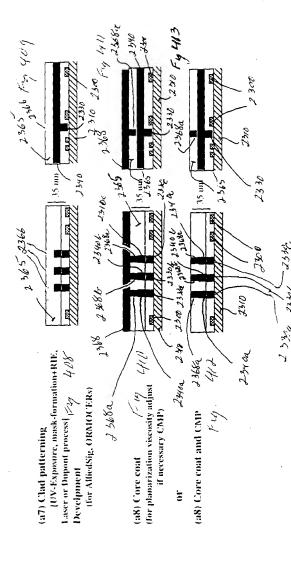




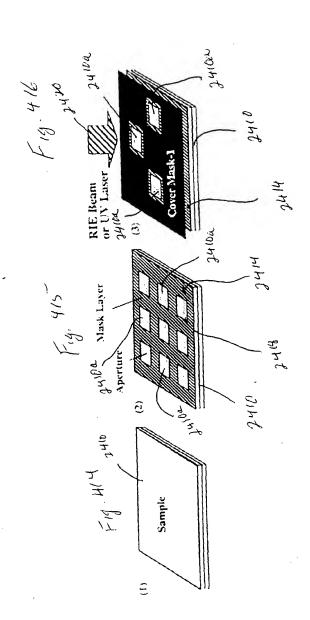


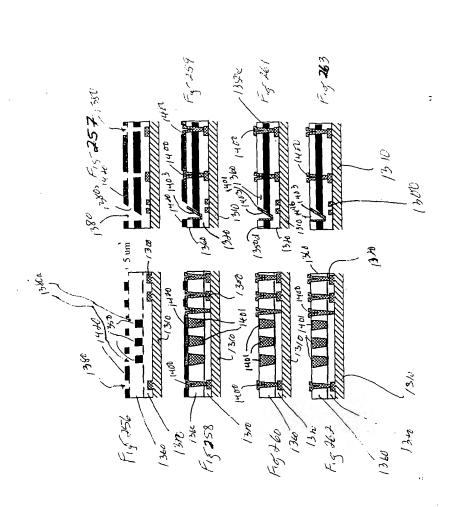


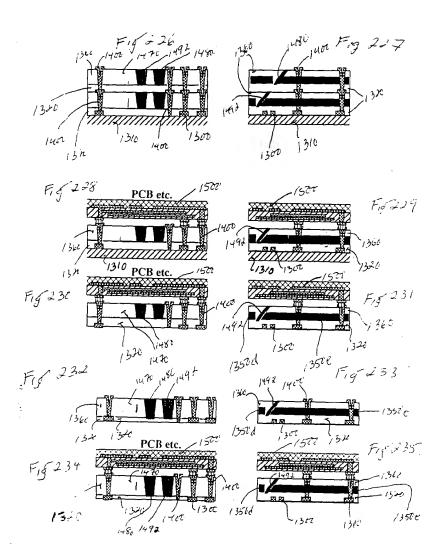


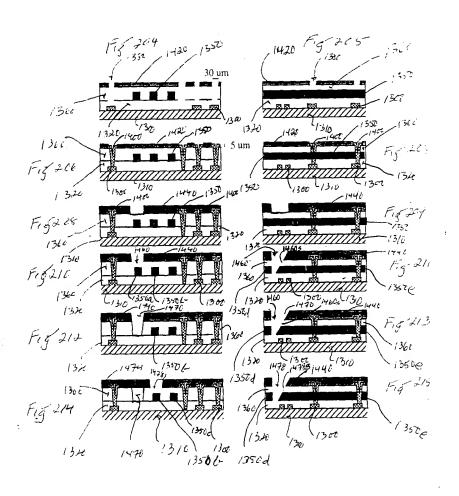


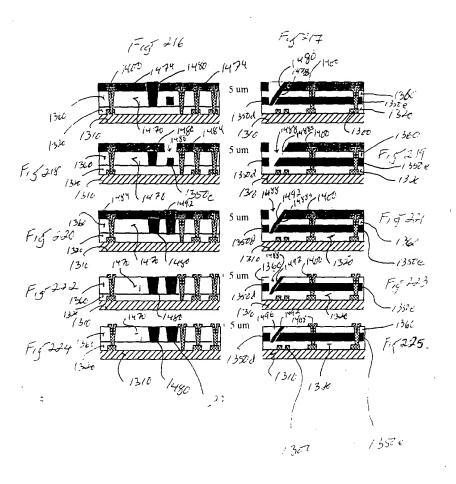
In the case of multi layer (a1, a5-a8) or (a5-a8) process is repeated on the (a8).

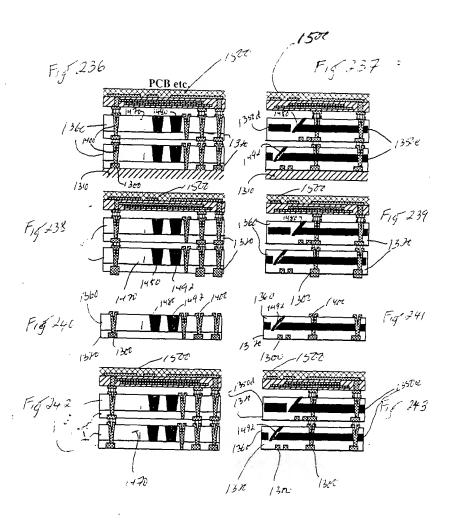


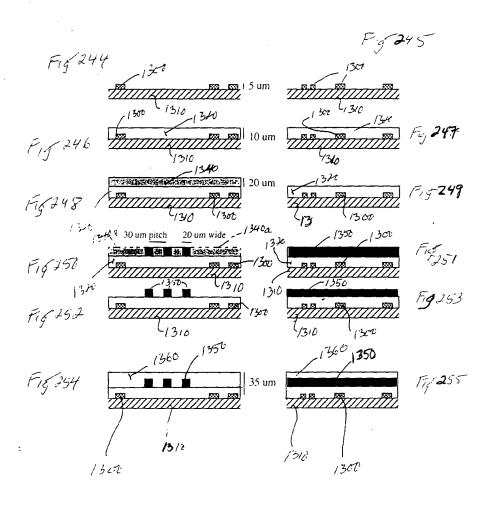


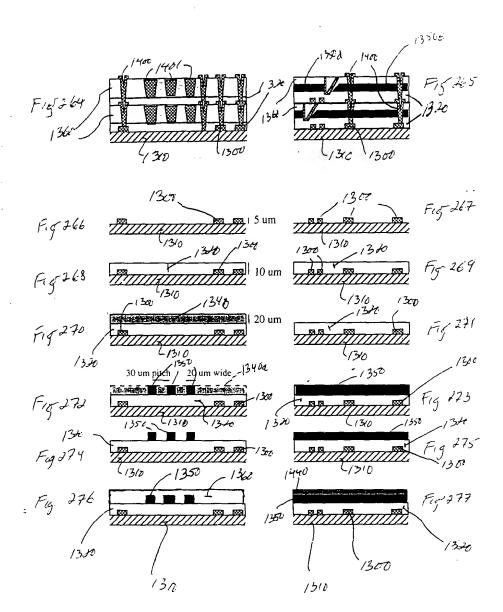


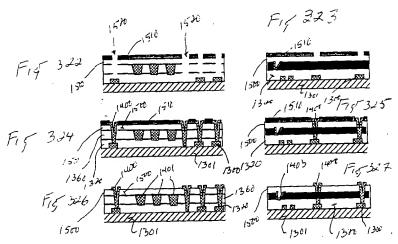




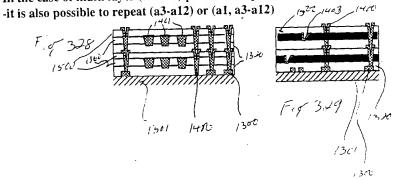


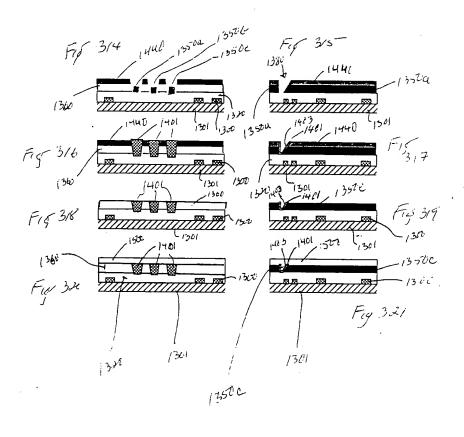


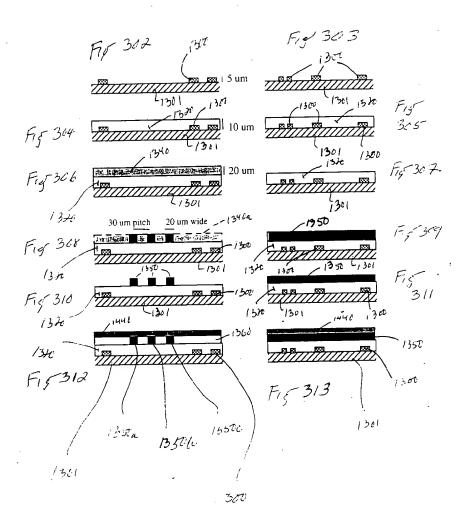


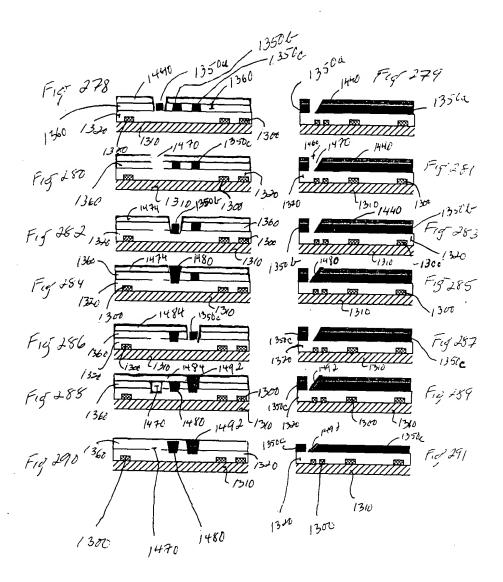


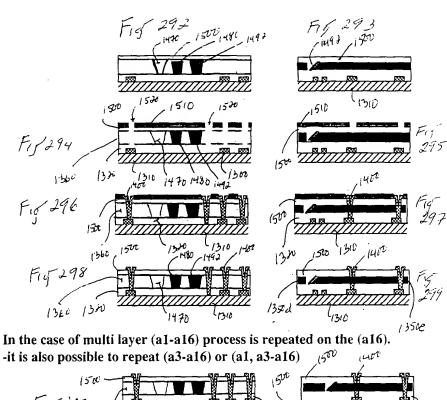
In the case of multi layer (a1-a12) process is repeated on the (a12).



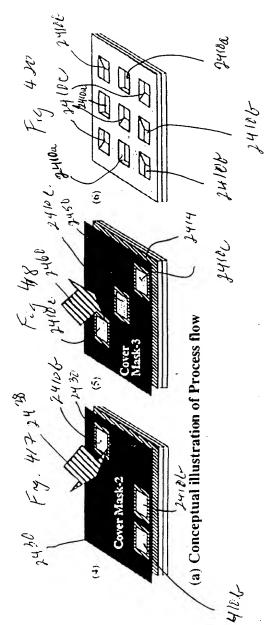








1500 | 1300 | 1300 | 1300 | 1492 | 1300 | 1300 | 1492 | 1300 | 1300 | 1492 | 1300 | 1300 | 1300 | 1492 | 1300 | 1492 | 1300 | 1492 | 1300 | 1492 | 1300 | 1492 | 1300 | 1492 | 1300 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 1492 | 14



F19. 421

